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J. Etoh et alFILING DATE
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U.S. PATENT DOCUMENTS

* EXAMINER INITIAL		DOCUMENT	DATE	NAME	CLASS	SUBCLASS	FILING DATE (If Appropriate)
<i>JHE</i>	AA	4,482,985	11/13/84	Itoh et al			
<i>JHE</i>	AB	5,148,255	09/15/92	Nakazato et al			
<i>JHE</i>	AC	4,730,122	03/08/88	Dreibelbis			
<i>JHE</i>	AD	4,994,688	02/19/91	Horiguchi et al			
<i>JHE</i>	AE	4,943,952	07/90	Terayama			
<i>JHE</i>	AF	5,046,052	09/91	Miyaji et al			
<i>JHE</i>	AG	5,227,697	07/93	Sakagami			
<i>JHE</i>	AH	4,961,166	10/90	Sato			
<i>JHE</i>	AI	4,962,482	10/90	Jinbo			
<i>JHE</i>	AJ	4,460,835	07/17/84	Masuoka			
<i>JHE</i>	AK	5,272,393	12/21/93	Horiguchi et al			

FOREIGN PATENT DOCUMENTS

		DOCUMENT	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
<i>JHE</i>	AL	60-167523	08/30/85	Japan			<input type="checkbox"/>	<input checked="" type="checkbox"/>
<i>JHE</i>	AM	57-172761	10/23/82	Japan			<input type="checkbox"/>	<input checked="" type="checkbox"/>
<i>JHE</i>	AN	59-151389	08/29/84	Japan			<input type="checkbox"/>	<input checked="" type="checkbox"/>
<i>JHE</i>	AO	63-211193	09/02/88	Japan			<input type="checkbox"/>	<input checked="" type="checkbox"/>
<i>JHE</i>	AP	60-242585	12/02/85	Japan			<input type="checkbox"/>	<input checked="" type="checkbox"/>

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

<i>JHE</i>	AR	IEEE Journal of Solid State Circuits, vol. 23, No. 1, pp 12-18, Feb. 1988.
<i>JHE</i>	AS	NEC 4-bit Microprocessor Handbook, p. 148 (no English translation), 1988.
<i>JHE</i>	AT	Hitachi IC Memory Data Book, Hitachi, Ltd., Tokyo, pp. 44-45, June 1987.

EXAMINER

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* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 608; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.